

APPLICABLE STANDARD						
RATING	OPERATING TEMPERATURE RANGE	-35°C TO +85 °C(NOTE 1)	STORAGE TEMPERATURE RANGE	-10°C TO +60°C(NOTE 3)		
	OPERATING HUMIDITY RANGE	20 % TO 80 % (NOTE 2)	STORAGE HUMIDITY RANGE	40 % TO 70 %(NOTE 3)		
	VOLTAGE	AC 150 V	APPLICABLE CONNECTOR	DF13-*S-1.25C		
	CURRENT	1 A	APPLICABLE CONTACT	DF13(G)-2630SCF, DF13-3032SCF		
SPECIFICATIONS						
ITEM		TEST METHOD		REQUIREMENTS	QT	AT
CONSTRUCTION						
GENERAL EXAMINATION		VISUALLY AND BY MEASURING INSTRUMENT.		ACCORDING TO DRAWING.	X	X
MARKING		CONFIRMED VISUALLY.			X	X
ELECTRIC CHARACTERISTICS						
CONTACT RESISTANCE		100 m A (DC OR 1000 Hz).		30 mΩ MAX.	X	—
INSULATION RESISTANCE		100 V DC.		500 MΩ MIN.	X	—
VOLTAGE PROOF		500 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.	X	—
MECHANICAL CHARACTERISTICS						
MECHANICAL OPERATION		30 TIMES INSERTIONS AND EXTRACTIONS.		① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	—
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.		① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	—
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.			X	—
ENVIRONMENTAL CHARACTERISTICS						
RAPID CHANGE OF TEMPERATURE		TEMPERATURE -55→ 5 TO 35→+85→ 5 TO 35 °C TIME 30→ 10 TO 5→ 30→ 10 TO15 min UNDER 5 CYCLES.		① CONTACT RESISTANCE: 30mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	—
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			X	—
RESISTANCE TO SOLDERING HEAT		1) REFLOW SOLDERING «REFLOW AREA» MAX250°C WITHIN 10 sec MIN 230°C WITHIN 60 sec «PREHEATING AREA» 170°C to 190°C 60 sec to 120 sec PUT THROUGH IN REFLOW FURNACE TWICE LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNECTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :350°C, SOLDERING TIME : 3sec. NO STRENGTH ON CONTACT.		NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	X	—
SOLDERABILITY		SOLDERED AT SOLDER TEMPERATURE, 245±3°C FOR INSERTION DURATION, 3sec.		SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMersed.	X	—
REMARKS						
NOTE1: INCLUDE THE TEMPERATURE RISING BY CURRENT						
NOTE2: NO CONDENSING						
NOTE3: APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE MOUNTED ON PCB. AFTER MOUNTED ON PCB BOARD, OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION.						
	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE	
△						
Unless otherwise specified, refer to IEC 60512.			APPROVED	HS.OKAWA	18.04.05	
			CHECKED	TS.FUKUSHIMA	18.04.05	
			DESIGNED	TS.KUMAZAWA	18.04.05	
			DRAWN	MK.INOUE	18.04.05	
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			DRAWING NO.		ELC-083664-75-00	
	SPECIFICATION SHEET		PART NO.	DF13-*P-1.25V(75)		
	HIROSE ELECTRIC CO., LTD.		CODE NO.	CL536	△	1/1